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(54) Title: METHOD AND DEVICE FOR ENCAPSULATING ELECTRONIC COMPONENTS USING UNDERPRESSURE

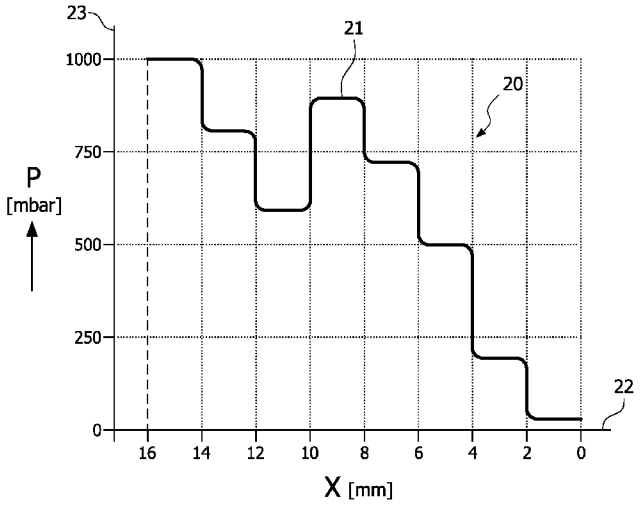


FIG. 2

(57) Abstract: The invention relates to a method for encapsulating electronic components mounted on a carrier using underpressure, comprising the processing steps of: A) placing an electronic component in a mould cavity, B) heating encapsulating material, C) displacing the encapsulating material to the mould cavity, D) filling the mould cavity, and E) curing the encapsulating material in the mould cavity. The invention also relates to a device with which such a method can be performed.

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